

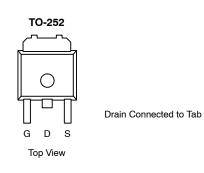
### NTD4858NAG-VB Datasheet

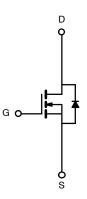
## N-Channel 20-V (D-S)175 °C MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	r <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>a</sup>		
20	0.0045 @ $V_{GS}$ = 4.5 V	100		
20	0.006 @ V <sub>GS</sub> = 2.5 V	90		

#### **FEATURES**

- Trench Power MOSFET
- 175°C Maximum Junction Temperature
- 100% R<sub>g</sub> Tested





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C UNLESS OTHERWISE NOTED)						
Parameter		Symbol	Limit	Unit		
Drain-Source Voltage		V <sub>DS</sub>	20	v		
Gate-Source Voltage		V <sub>GS</sub>	±15	V		
	$T_{C} = 25^{\circ}C$		100			
Continuous Drain Current <sup>a</sup>	$T_{C} = 100^{\circ}C$		80			
Pulsed Drain Current		I <sub>DM</sub>	200	A		
Continuous Source Current (Diode Conduction) <sup>a</sup>		IS	65			
	$T_{C} = 25^{\circ}C$		71			
Maximum Power Dissipation	T <sub>A</sub> = 25°C	P <sub>D</sub>	8.3 <sup>b, c</sup>	W		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to 175	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
	$t \le 10$ sec.		15	18			
Maximum Junction-to-Ambient <sup>b</sup>	Steady State	R <sub>thJA</sub>	40	50	°C/W		
Maximum Junction-to-Case	•	R <sub>thJC</sub>	1.75	2.1			

Notes

a. Package Limited

b. Surface Mounted on 1" x 1" FR4 Board

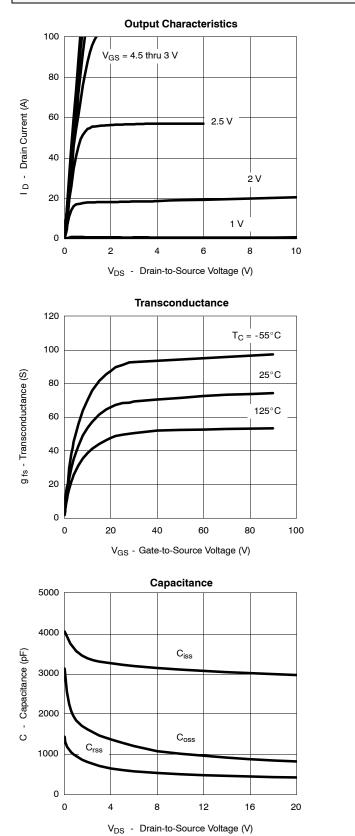
c.  $t \leq 10 \text{ sec}$ 

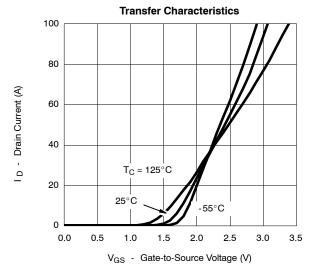
Parameter	Symbol	Test Condition Min		Тур <sup>а</sup>	Max	Unit	
Static					•	•	
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS}$ = 0 V, $I_D$ = 250 $\mu$ A	20			v	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$	0.5		1.5		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			±100	nA	
Zero Gate Voltage Drain Current		$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1		
	I <sub>DSS</sub>	$V_{DS}$ = 20 V, $V_{GS}$ = 0 V, $T_{J}$ = 125 °C			50	μΑ	
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	$V_{DS}$ = 5 V, $V_{GS}$ = 4.5 V	100			Α	
		$V_{GS}$ = 4.5 V, I <sub>D</sub> = 20 A		0.0045		Ω	
Drain-Source On-State Resistance <sup>b</sup>	r <sub>DS(on)</sub>	$V_{GS}$ = 4.5 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C		0.0055			
		$V_{GS}$ = 2.5 V, I <sub>D</sub> = 20 A		0.006		1	
Forward Transconductanceb	9 <sub>fs</sub>	$V_{DS} = 5 V, I_{D} = 40 A$	20			S	
Dynamic <sup>a</sup>							
Input Capacitance	C <sub>iss</sub>			3660		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS}$ = 0 V, $V_{DS}$ = 20 V, f = 1 MHz	-	730			
Reverse Transfer Capacitance	C <sub>rss</sub>			375			
Total Gate Charge <sup>c</sup>	Qg			26	35	nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS}$ = 10 V, $~V_{GS}$ = 4.5 V, $I_{D}$ = 40 A		5			
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			7		1	
Gate Resistance	Rg		1		3.7	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			20	35	- ns	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 10 \text{ V}, \text{ R}_{I} = 0.25 \Omega$		120	190		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$\begin{array}{l} V_{DD} = 10 \; V, \; R_L = 0.25 \; \Omega \\ I_D  \cong  40 \; A, \; V_{GEN} = 4.5 \; V, \; R_G = 2.5 \; \Omega \end{array}$		45	70		
Fall Time <sup>c</sup>	t <sub>f</sub>			20	35		
Source-Drain Diode Ratings an	d Characteristi	c (T <sub>C</sub> = 25°C)					
Pulsed Current	I <sub>SM</sub>				100	А	
Diode Forward Voltage <sup>b</sup>	V <sub>SD</sub>	I <sub>F</sub> = 100 A, V <sub>GS</sub> = 0 V		1.2	1.5	V	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 40 A, di/dt = 100 A/μs			70	ns	

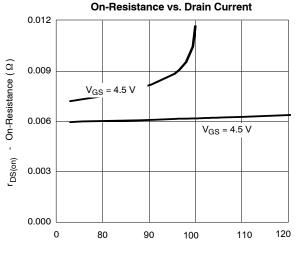
Bsemi



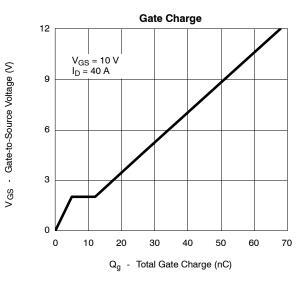
#### TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)



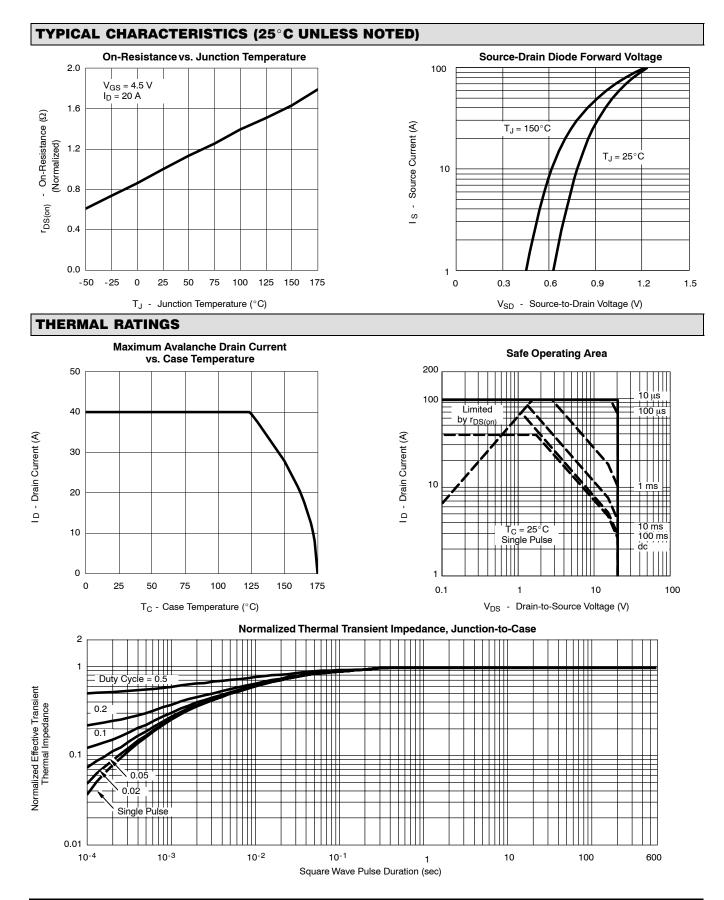






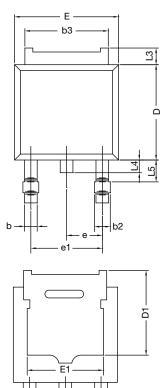


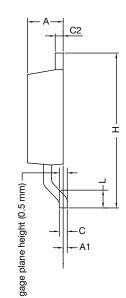






## **TO-252AA CASE OUTLINE**





	MILLIN	METERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	-	
E	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	BSC	BSC		
e1	4.56 BSC		0.180 BSC		
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12- DWG: 534	0247-Rev. M, 7	24-Dec-12			

Note

• Dimension L3 is for reference only.



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